confidential

Electrical Conductive Adhesive
(Solder Replacement)

Namics Corporation
July 2016

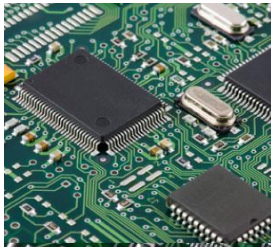
Features and Benefits

- Replacement for Lead Containing Solders
- Replacement for Britteling Lead Free Solders
  - Low Volume Resisitivity
  - High Adhesion Strength
  - High Flexible Bond Line
  - Vibration Resistance
  - Excellent Temperature Cycling Resistance
  - High Moisture Stability

Products

H9626 (Printing)
H9626 D (Dispensing)

General Assembly

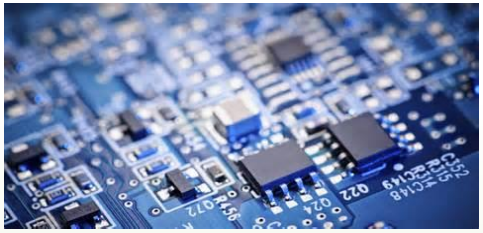


XH9674 (Printing)
XH9674D (Dispensing)

Tin Plated and High Performance Assembly

XH9698-3 (Printing)
XH9698D-3 (Dispensing)

High Temperature Stable Assembly



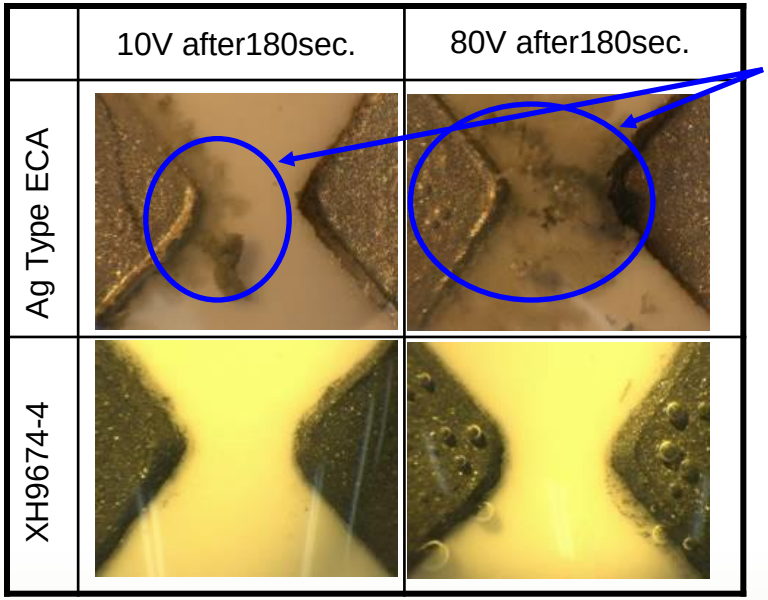
Product Characteristics

			H9626	H9626D	XH9674	XH9674D	XH9698-3	XH9698D-3
Processing			Printing	Dispensing	Printing	Dispensing	Printing	Dispensing
Application			General Purpose, Flexible Bonds		Tin Plated Components, Ag Migration Contol		High Thermal Stability, Vibration Resistant	
Filler Type			Ag		AgSn		Ag	
Viscosity @ 25°C		Pa.s	230	47	450	54	250	50
TI			3,1	4,9	1,7	4,3	6,0	6,7
Tg		°C	120	115	125	125	205	205
CTE	< Tg	ppm / °K	40	35	55	45	45	50
	> Tg	ppm / °K	110	110	110	115	85	70
Storage Modulus		GPa	6,0	6,5	10,0	7,5	6,2	8,0
Contact Resistance		mOhm	12,1	11,9	9,6	2,0	6,0	6,0
Adhesion Strength*		N / mm²	40	40	45	50	55	40
Pot Life @ 25°C		Days	7	3	1	1		
Curing		Min. @ °C	30 / 150	30 / 150	30 / 150	30 / 150	30 / 200	30 / 200

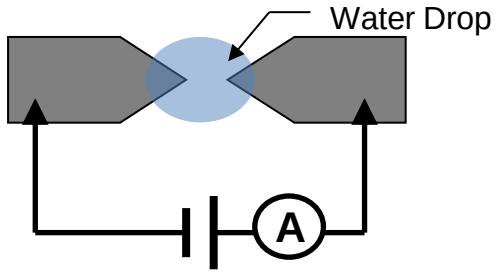
* Al_2O_3 Substrate, Size 3216

XH9674 Migration Stability

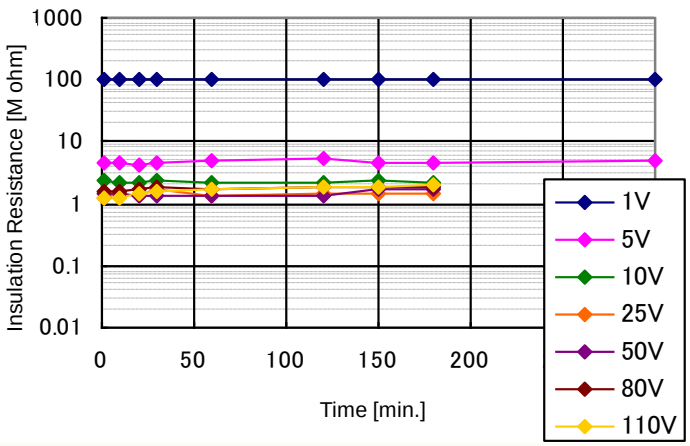
As XH9674-4 contains AgSn filler,
it does prevent Ag-migration.



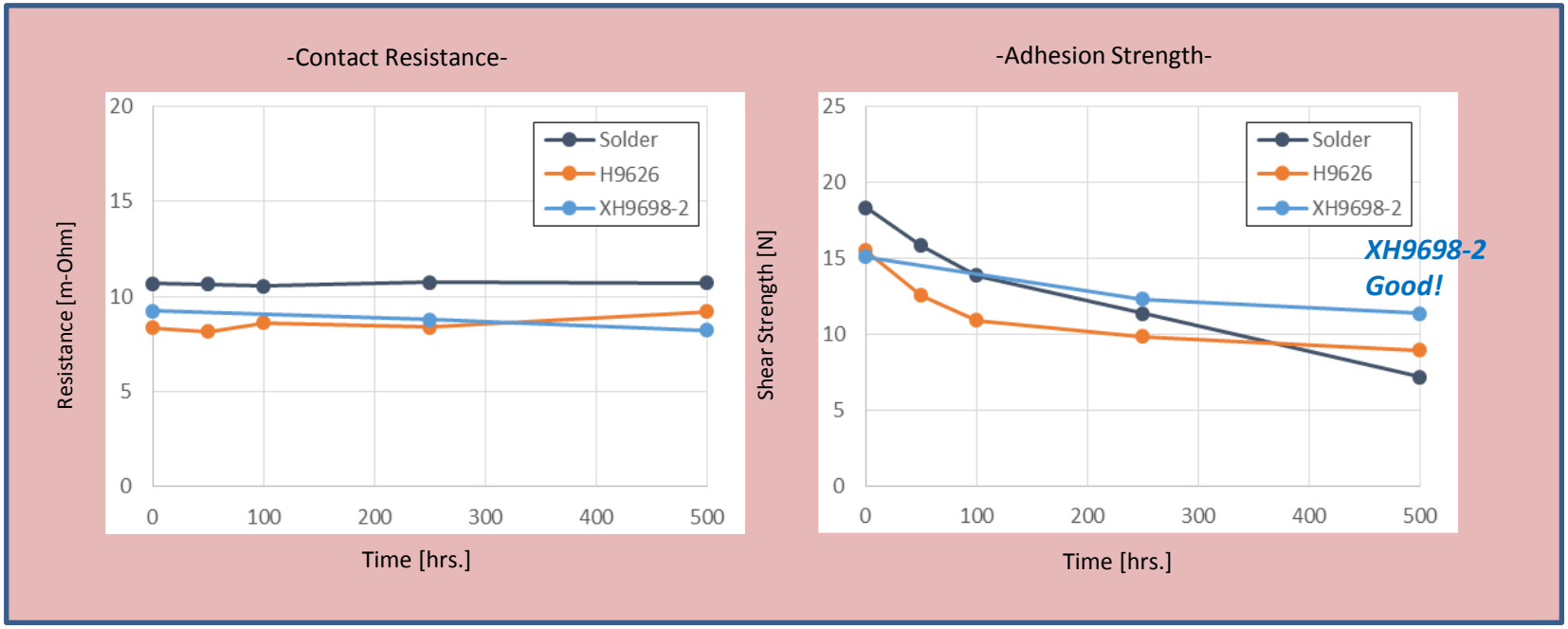
Water Drop Test



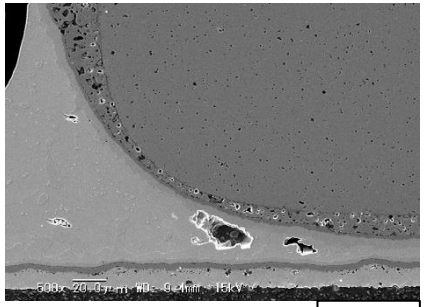
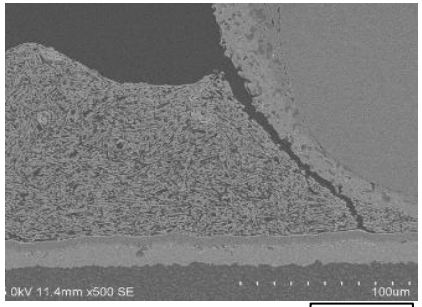
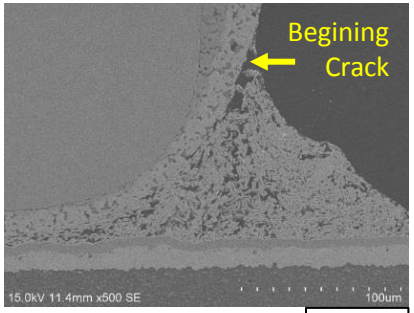
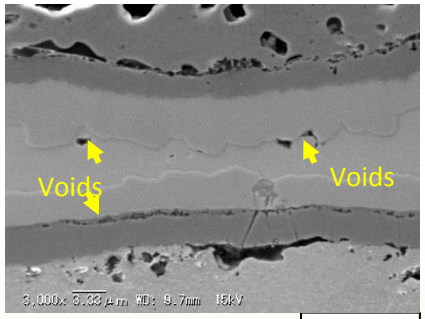
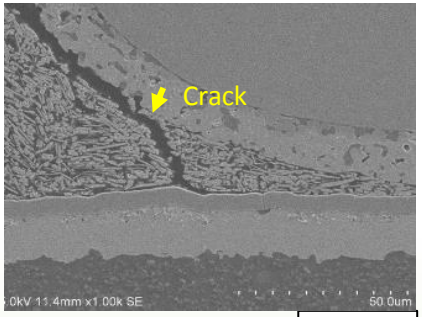
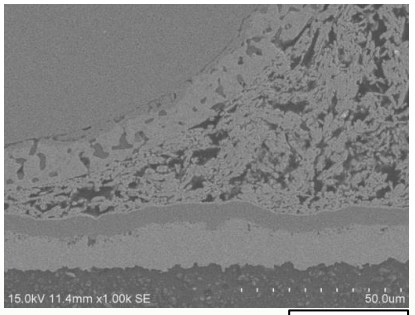
XH9674-4 Insulation Resistance



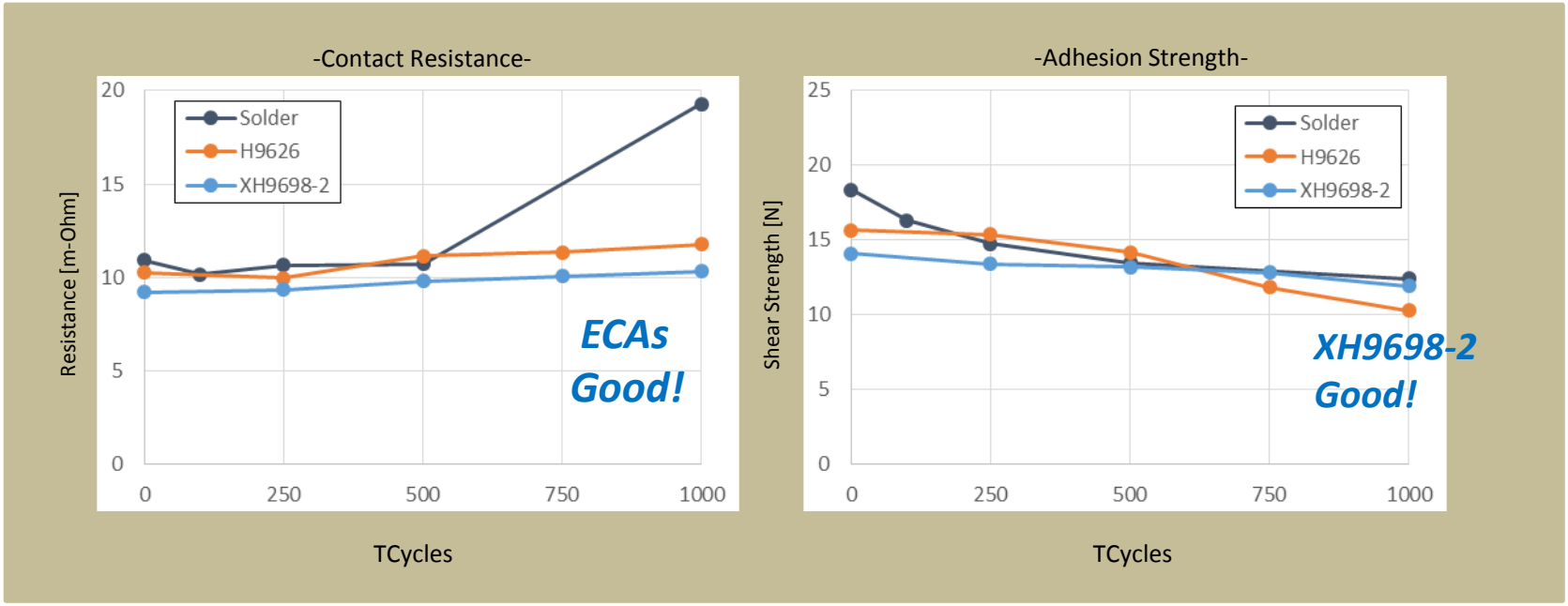
High Temperature Storage, 200°C



High Temperature Storage, 200°C

Solder	H9626 Series	XH9698 Series
		
x500	x500	x500
		
x3000	x1000	x1000

TCT -55°C ⇔ +175°C



Stable Contact Resistance for ECA‘s

THANK YOU